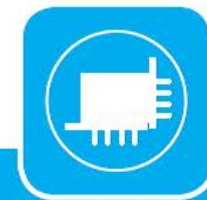




**Notre expertise**  
est votre meilleur partenaire

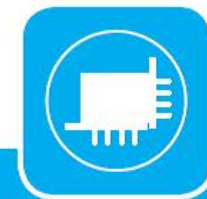
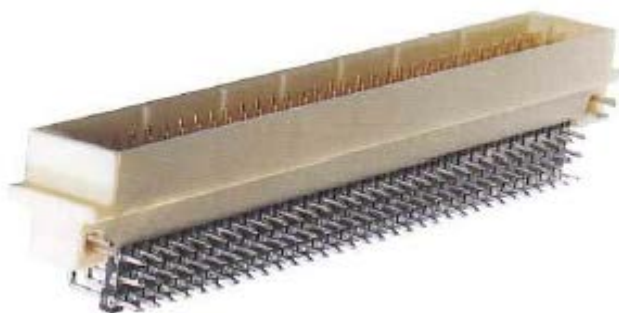
 **Cotelec**  
Composants & Technologies pour l'Electronique

**Technologie** Solder Flux Bearing Lead



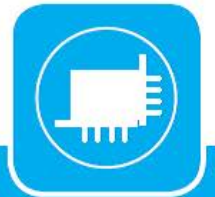
# Technologie Solder Flux Bearing Lead

## Applications connectique



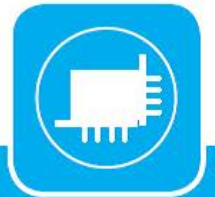
# Technologie Solder Flux Bearing Lead

- ❑ Une solution innovante pour l'assemblage de connecteurs sur PCB



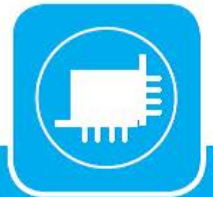
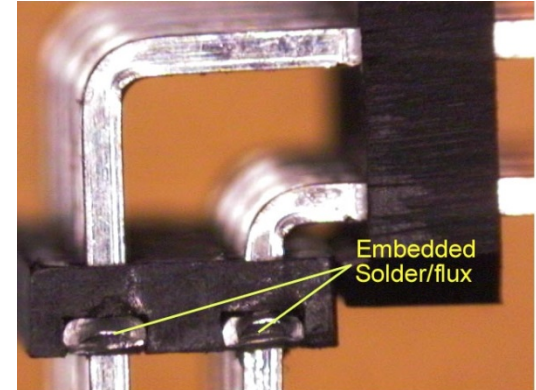
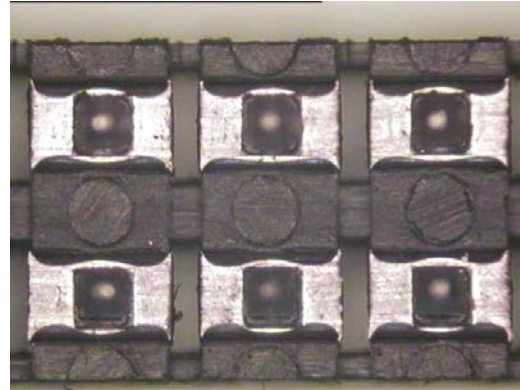
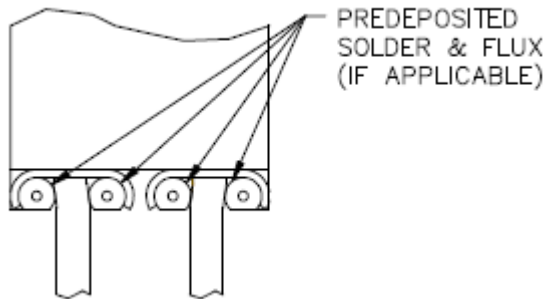
# Technologie Solder Flux Bearing Lead

- ❑ Animation [présentation](#) process S.B.L.



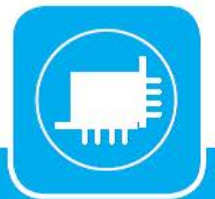
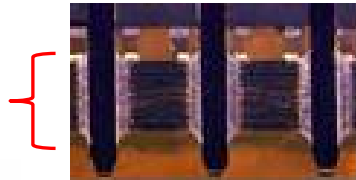
## Technologie Solder Flux Bearing Lead

- Rendre votre processus de fabrication compatible en refusions double face.
- Apport de soudure et flux sur chaque sorties de contacts.



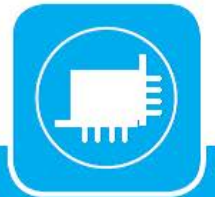
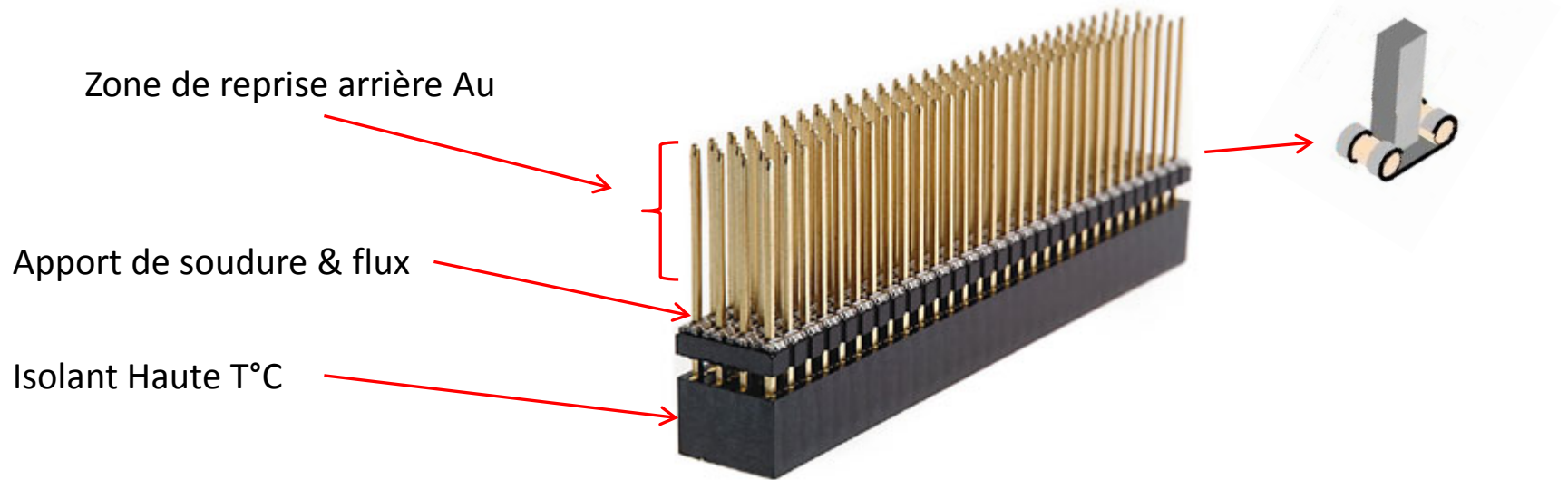
## Technologie Solder Flux Bearing Lead

- Process refusion compatible pour des connecteurs avec broches traversantes en une seule passe et avec d'autres composants CMS.
- Compatible avec les équipements et process de soudure CMS conventionnels.
- Suppression d'opérations supplémentaires de brasage vague, soudure sélective, reprise soudure manuelle.
- Sans soudure, patte à braser ou flux additionnels.
- Joints de soudure suivant directives IPC classe III.



## Technologie Solder Flux Bearing Lead

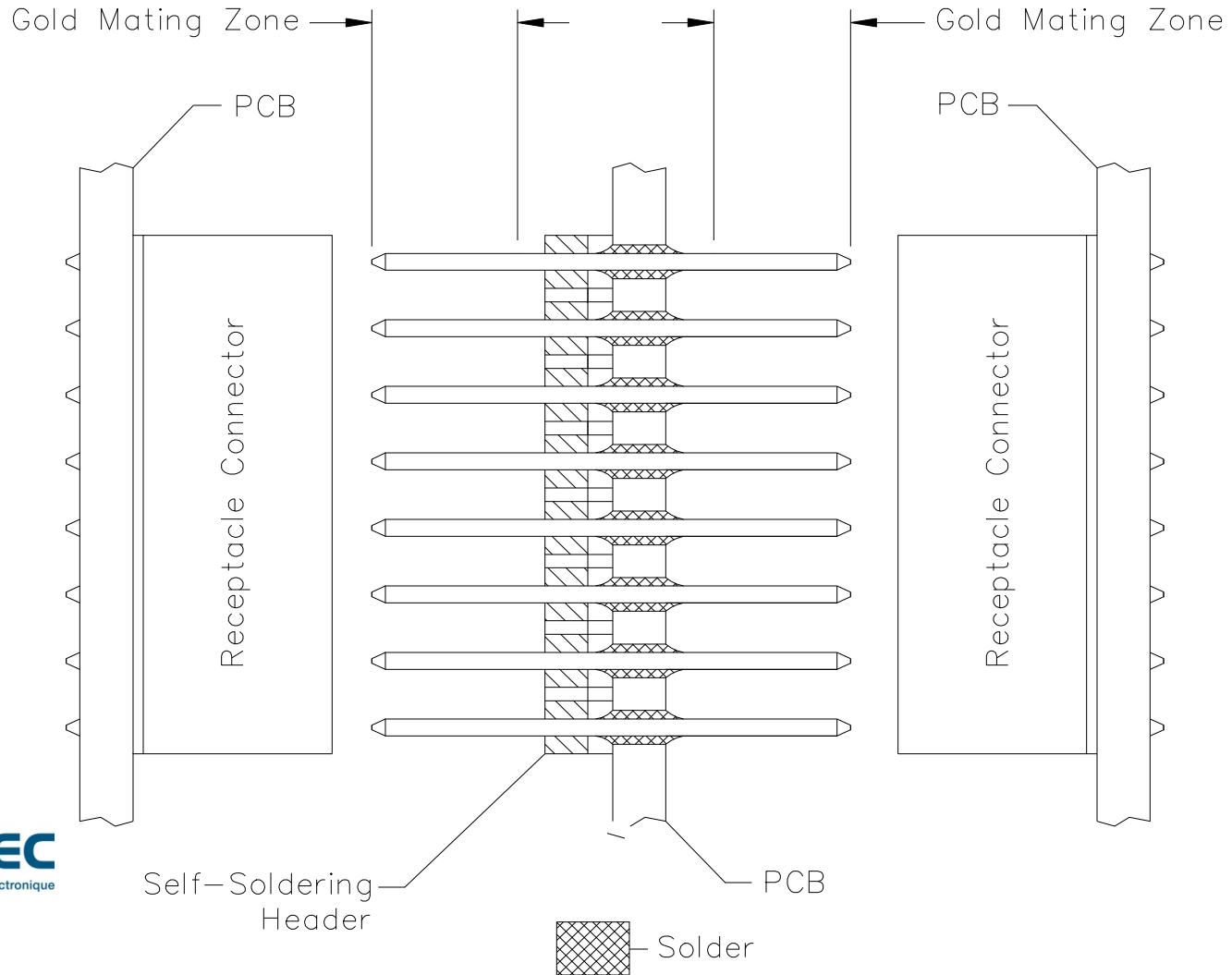
- Une alternative à la technologie Connexion Insérées en force (connections empilables, reprises arrières).





Interconnection  
Systems

# Connections empilables





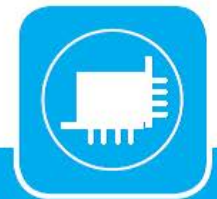
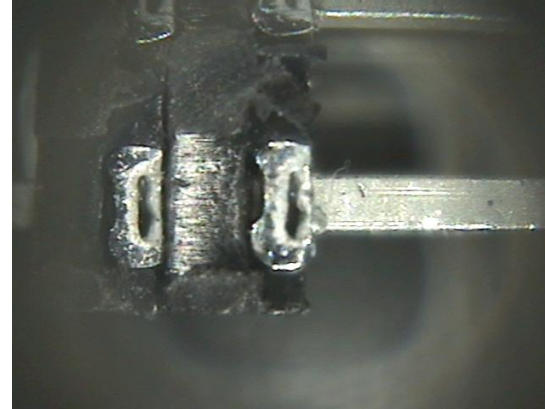
## Technologie Solder Flux Bearing Lead

- Une alternative au process « Pin In Past » et ses limitations, complications (pontets de soudure, pas de reprise arrière, mise en œuvre...)
- Volume de soudure et flux adapté selon épaisseur du PCB.

### LEAD-FREE ALLOY

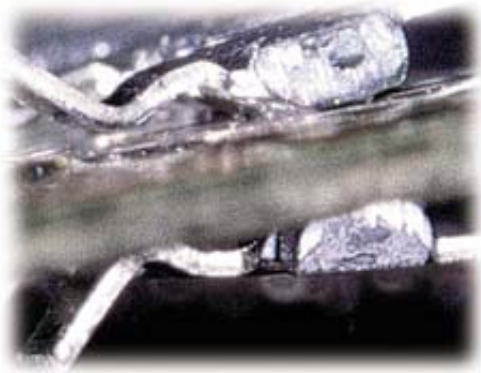
NAME: **SAC305**

SAC Alloys is compatible with all major electronic grade fluxes on the market today, and is available in paste and wire form in no-clean, water soluble and rosin chemistries.



## Technologie Solder Flux Bearing Lead

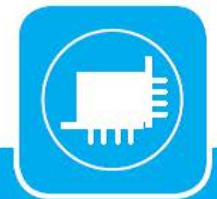
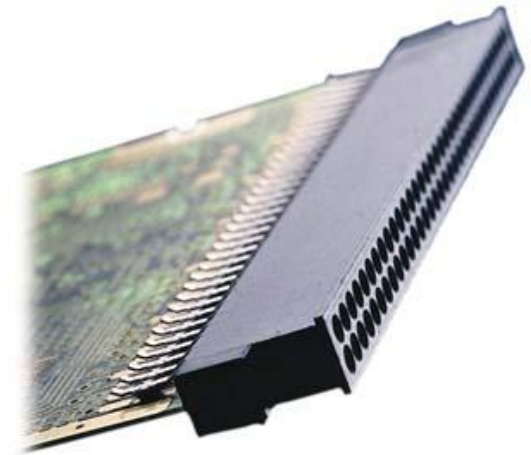
- Refusion de connecteurs traversants, multi-rangées (3 rangées ou plus) au pas de 2,54 ou 2,00 mm.
- Refusion possible de connecteurs encartables sur PCB.



Avant refusion

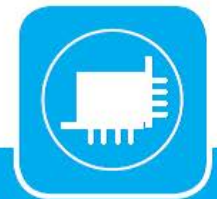
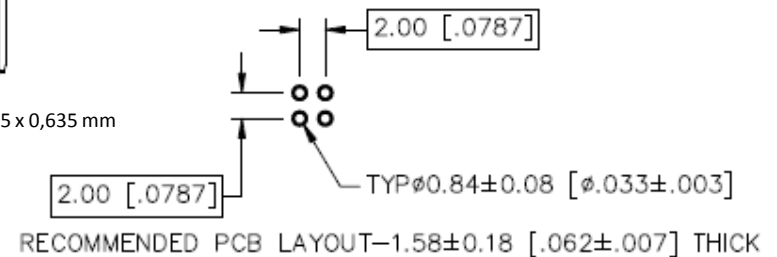
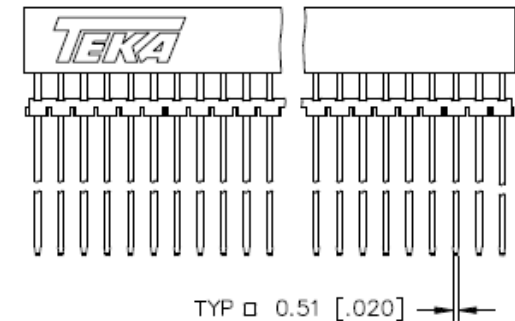
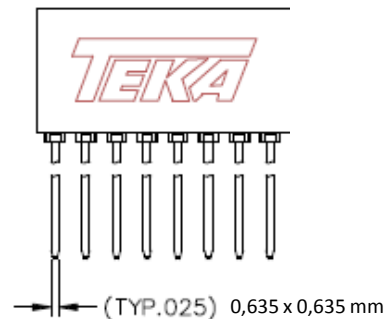
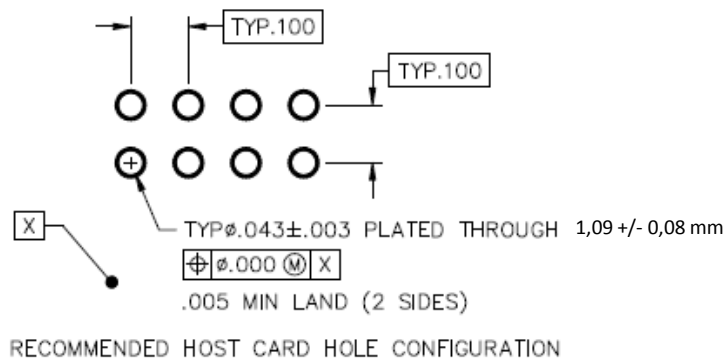


Après refusion



## Technologie Solder Flux Bearing Lead

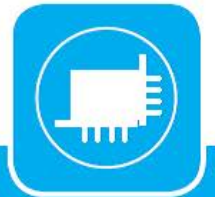
- Produits standards RoHS,
- Versions Pb sur demande.
- Pas de modification des trous sur PCB



## Technologie Solder Flux Bearing Lead

Technologie innovante qui permet une mise en place du connecteur plus facile et plus rapide.

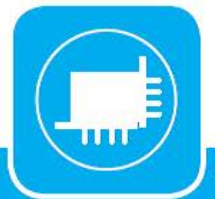
Les connecteurs TEKA dotés de la technologie SBL peuvent être utilisés en remplacement de connecteurs traditionnels.



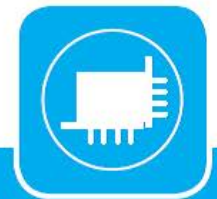
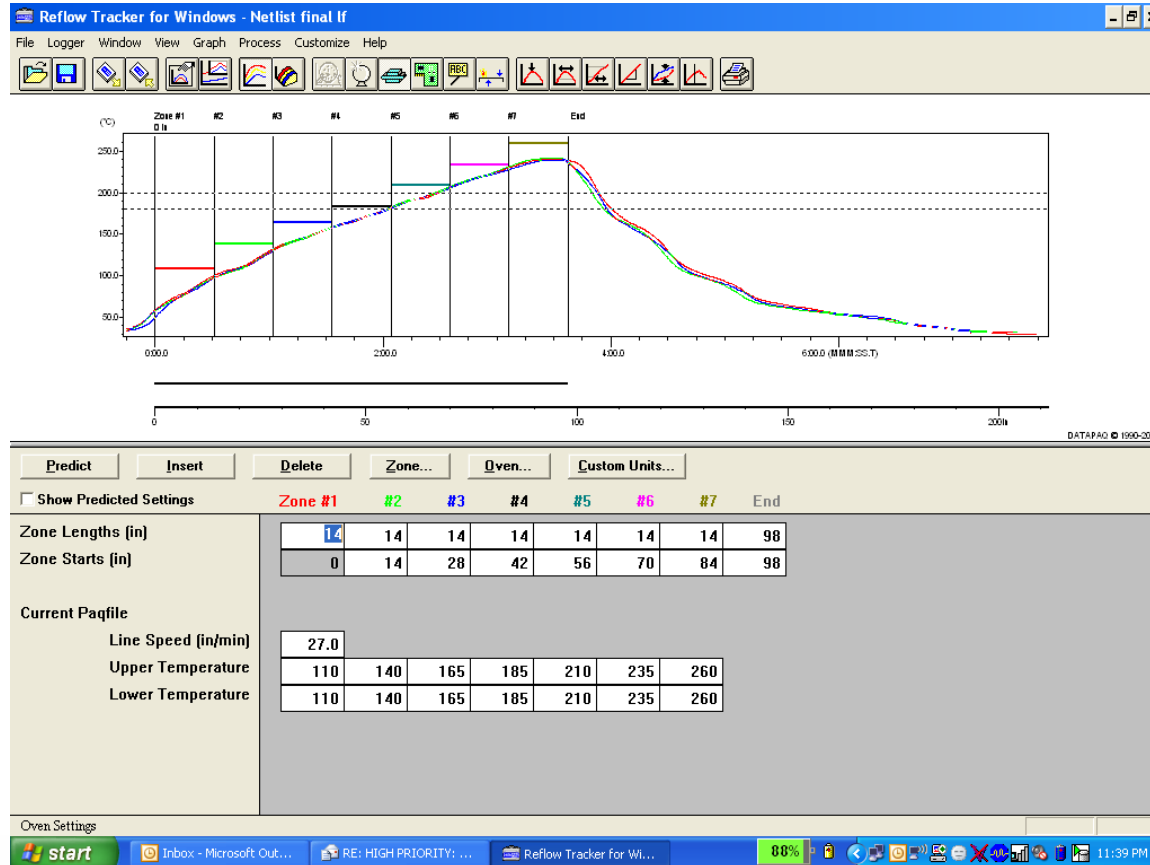
## Technologie Solder Flux Bearing Lead

Plusieurs facteurs sont à prendre en compte.

- Type de four.
- Nombre de zone de chauffe.
- Configuration de la carte.
- Type de composants et leur emplacement physique sur PCB (diffusion de T°C).



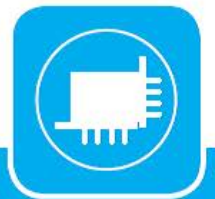
# Courbe de Température type





## Technologie Solder Flux Bearing Lead

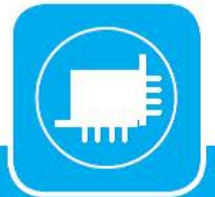
### Avantages:

- **Utilisation de connecteurs traversant en process refusion.**
- **Meilleure tenue mécanique des connecteurs traversant, sur PCB / CMS.**
- **Suppression des opérations de reprise.**
- **Gain en temps et coût fabrication.**



## Technologie Solder Flux Bearing Lead Connectique proposée par TEKA en SBL:

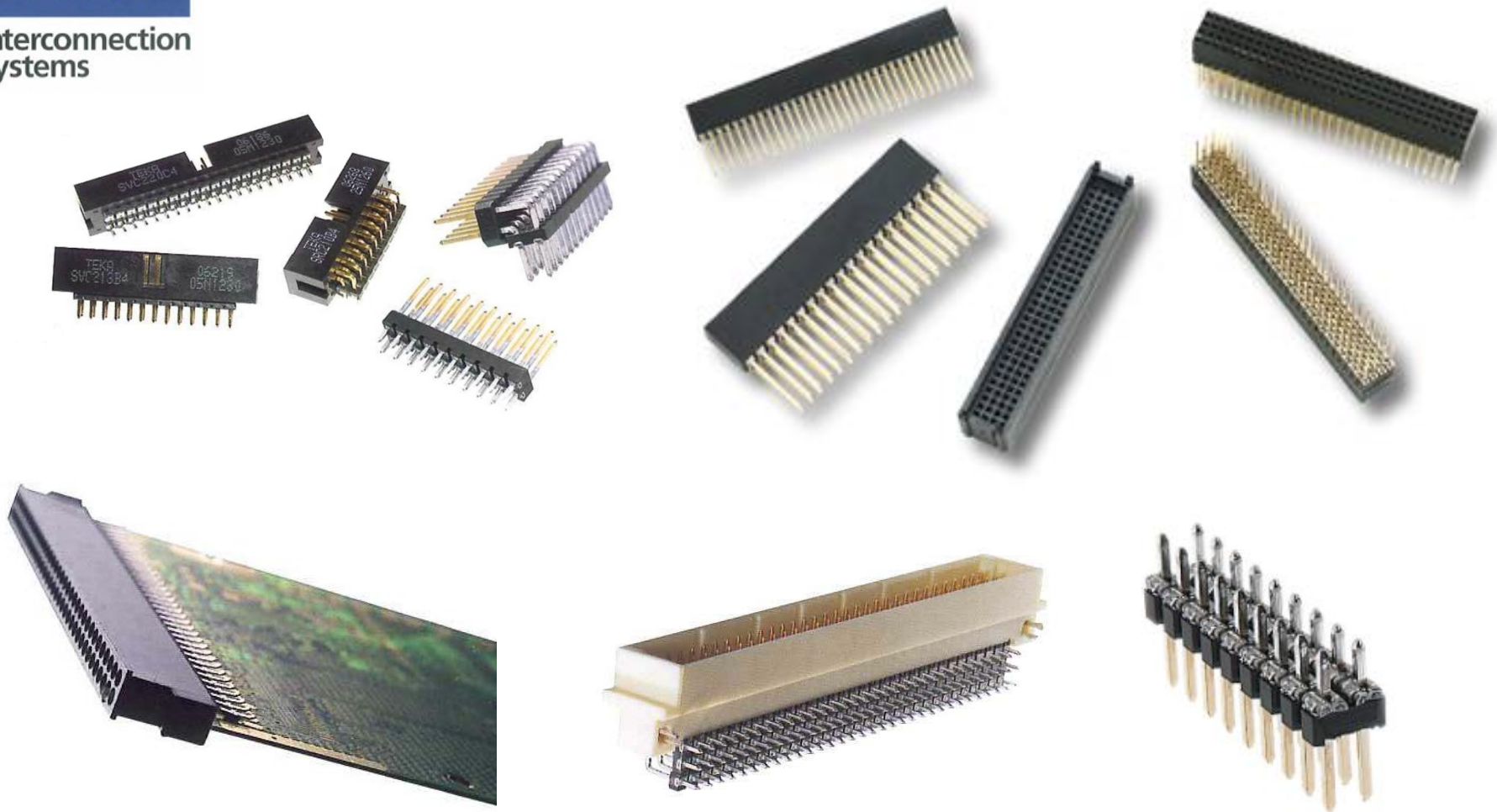
- PC104 / PC104+ 
- Embases « HE10 / DIN 41651 » bas profil.
- Embases mâles pas de 2,54 & 2,0 mm.
- DIN 4162 mâle Type C coudé.
- PC Card & CompactFlash femelle. 





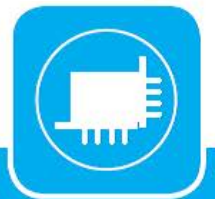


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**Technologie** Solder Flux Bearing Lead





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**DUXR2.E151639**  
**Communications-circuit Accessories - Component**

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**TEKA INTERCONNECTION SYSTEMS** E151639  
 100 PIONEER AVE  
 WARWICK, RI 02888 USA

**Communication connectors.** Series: 8XX, 9XX, 10XX, 13XX, 20XX, 22XX, 24XX, 25PC2101XX, 25XX, 26XX, 27XX, 28XX, 29XX, 31XX, 35XX, 45XX, 46XX, 47XX, 52XX, 58XX, 60XX, 74XX, 78XX, 82XX, 86XX, 1101XX, 1103XX, 2145XX, 3695XX, 3769XX, 4044XX, 5235XX, 5425XX, 5525XX, 8801XX, 8804XX, C, C/2, R, R/2, S45, S46, where X is a number. All series may be followed by suffix letters or numbers.

Marking: Company name and series designation.  
 Last updated on 2005-10-12

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June 2, 2014

**Re: European Union REACH Regulation concerning Substances of Very High Concern (SVHC)**

We hereby Confirm that Teka Interconnection Systems products and manufacturing processes are in compliance with the above referenced REACH regulation restricting the use of SVHCs. This information is provided based upon reasonable inquiry of our suppliers and represents our current actual knowledge based upon the information provided by our suppliers.

In regard to the SVHC substances identified in the ECHA press release (PR/08/38) dated November 4<sup>th</sup>, 2008, and Annex XVII, none of the identified substances are intentionally added to Teka Interconnection Systems products or used in their manufacture. As Teka Interconnection Systems products are free of intentionally added SVHC and based on the "article" criteria stipulated in the REACH regulation, the products manufactured by Teka Interconnection Systems are interpreted to be exempt from substance registration and compliant with REACH EC 1907/2006.

Teka's sole liability for incorrectly certifying a product shall be either the replacement of the Teka product or, alternatively and in the sole discretion of Teka, return of the purchase price paid for the relevant Teka Product.



Charlie Fay  
 Quality Manager

## RoHS Customer Assistance

### Teka Interconnection Systems RoHS Compliance

The European Union has passed legislation restricting the use of hazardous substances in electrical and electronic products. This legislation, also known as the Restriction on Hazardous Substances (RoHS) directive, places restrictions on the use of lead, hexavalent chromium, cadmium, mercury, polybrominated biphenyl (PBB) and polybrominated diphenyl ethers (PBDE). In accordance to this directive, Teka Interconnection Systems intends to achieve compliance by evaluating our materials and processes and making changes where necessary.

#### Restricted Materials:

**Lead** - No intentional additions of lead will be made. Unintentional additions of lead may occur as an impurity at levels equal to or less than 1000 parts per million (PPM).

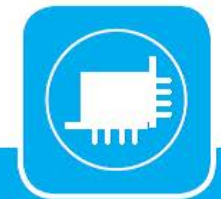
**Hexavalent Chromium** - No intentional additions of hexavalent chromium will be made to any Teka Interconnection Systems product. Unintentional additions of hexavalent chromium may exist in levels equal to or less than 100 parts per million (PPM).

**PBB (Polybrominated Biphenyl) / PBDE (Polybrominated Diphenyl Ethers)** - At this time, no PBB or PBDE materials are used in any Teka Interconnection Systems product. No intentional additions of PBB or PBDE materials will be made to any Teka Interconnection Systems Product.

**Cadmium** - Cadmium will not be intentionally added to any Teka Interconnection Systems product. Cadmium may exist as an unintentional additive in levels equal to or less than 100 parts per million (PPM).

**Mercury** - At this time, mercury is not intentionally used in any Teka Interconnection Systems product. No intentional additions of mercury will be made to any Teka Interconnection Systems product. Mercury may exist as an unintentional additive in levels less than or equal to 100 parts per million (PPM).

Please note: Minimum order quantities may vary from standard on RoHS compliant parts.



**N'hésitez pas à nous contacter pour tout complément d'information nécessaire.**



**Franck SUBTIL**

Responsable Département Connectique

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[www.tekais.com](http://www.tekais.com)

